FEATURES:

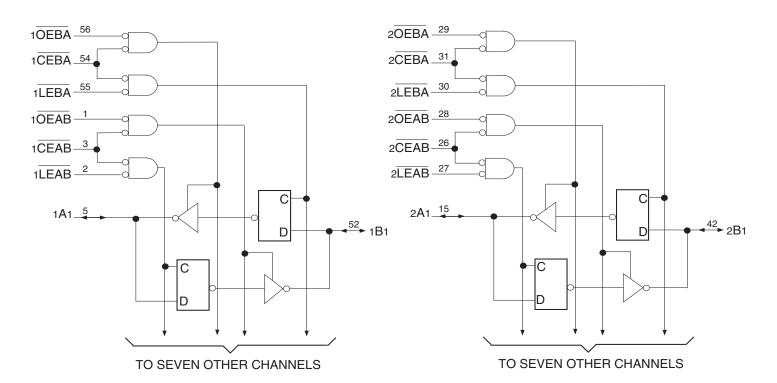
- 0.5 MICRON CMOS Technology
- · High-speed, low-power CMOS replacement for ABT functions
- Typical tsk(o) (Output Skew) < 250ps
- Low input and output leakage ≤1µA (max.)
- $VCC = 5V \pm 10\%$
- · High drive outputs (-32mA IOH, 64mA IOL)
- Power off disable outputs permit "live insertion"
- Typical Volp (Output Ground Bounce) < 1.0V at Vcc = 5V, TA = 25°C
- Available in SSOP and TSSOP packages

DESCRIPTION:

The FCT16543T 16-bit latched transceivers are built using advanced dual metal CMOS technology. These high-speed, low-power devices are organized as two independent 8-bit D-type latched transceivers with separate input and output control to permit independent control of data flow in either direction. For example, the A-to-B Enable (xCEAB) must be low inorder to enter data from the A port or to output data from the B port. xLEAB controls the latch function. When xLEAB is low, the latches are transparent. A subsequent low-to-high transition of xLEAB signal puts the A latches in the storage mode. xOEAB performs output enable function on the B port. Data flow from the B port to the A port is similar but requires using xCEBA, xLEBA, and xOEBA inputs. Flow-through organization of signal pins simplifies layout. All inputs are designed with hysteresis for improved noise margin.

The FCT16543T is ideally suited for driving high-capacitance loads and low-impedance backplanes. The output buffers are designed with power off disable capability to allow "live insertion" of boards when used as backplane drivers.

FUNCTIONAL BLOCK DIAGRAM

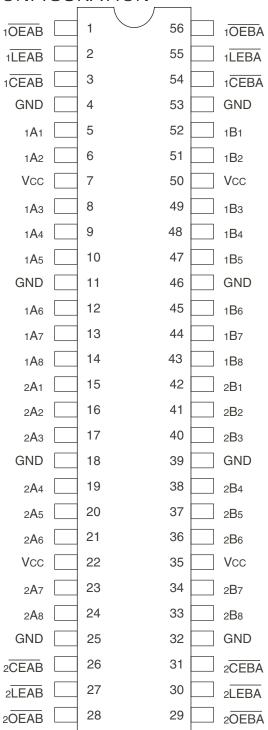


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INDUSTRIAL TEMPERATURE RANGE

JULY 2017

PIN CONFIGURATION



TOP VIEW

Package Type	Package Code	Order Code
TSSOP	PAG56	PAG
SSOP	PVG56	PVG

PIN DESCRIPTION

Pin Names	Description
xŌĒĀB	A-to-B Output Enable Input (Active LOW)
xŌĒBĀ	B-to-A Output Enable Input (Active LOW)
xCEAB	A-to-B Enable Input (Active LOW)
xCEBA	B-to-A Enable Input (Active LOW)
xĪĒĀB	A-to-B Latch Enable Input (Active LOW)
xLEBA	B-to-A Latch Enable Input (Active LOW)
хАх	A-to-B Data Inputs or B-to-A 3-State Outputs
хВх	B-to-A Data Inputs or A-to-B 3-State Outputs

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to 7	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
Tstg	Storage Temperature	-65 to +150	°C
Іоит	DC Output Current	-60 to +120	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
 permanent damage to the device. This is a stress rating only and functional operation
 of the device at these or any other conditions above those indicated in the operational
 sections of this specification is not implied. Exposure to absolute maximum rating
 conditions for extended periods may affect reliability.
- 2. All device terminals except FCT162XXX Output and I/O terminals.
- 3. Outputs and I/O terminals for FCT162XXX.

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	3.5	6	pF
Соит	Output Capacitance	Vout = 0V	3.5	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

FUNCTION TABLE(1, 2)

For A-to-B (Symmetric with B-to-A)

	Inputs		Latch Status	Output Buffers
xCEAB	xLEAB	xŌĒĀB	xAx to xBx	хВх
Н	Х	Х	Storing	Z
Х	Н	Х	Storing	Χ
L	L	L	Transparent	Current A Inputs
L	Н	L	Storing	Previous* A Inputs
L	L	Н	Transparent	Z
Ĺ	H	H	Storing	Ž

NOTES:

1. * Before xLEAB LOW-to-HIGH Transition

H = HIGH Voltage Level

L = LOW Voltage Level

X = Don't Care

 A-to-B data flow shown; B-to-A flow control is the same, except using xCEBA, xLEBA and xOEBA.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC = $5.0V \pm 10\%$

Symbol	Parameter	Test Conditions ⁽	1)	Min.	Typ. ⁽²⁾	Max.	Unit
VIH	Input HIGH Level	Guaranteed Logic HIGH Level		2	_	-	V
VIL	Input LOW Level	Guaranteed Logic LOW Level		_	_	0.8	V
Iн	Input HIGH Current (Input pins) ⁽⁵⁾	Vcc = Max.	VI = VCC	_	_	±1	μA
	Input HIGH Current (I/O pins) ⁽⁵⁾			_	_	±1	
lıL	Input LOW Current (Input pins)(5)		VI = GND	_	_	±1	
	Input LOW Current (I/O pins) ⁽⁵⁾			_	_	±1	
lozh	High Impedance Output Current	Vcc = Max.	Vo = 2.7V	_	_	±1	μΑ
lozl	(3-State Output pins) ⁽⁵⁾		Vo = 0.5V	_	_	±1	
VIK	Clamp Diode Voltage	Vcc = Min., IIN = -18mA		_	-0.7	-1.2	V
los	Short Circuit Current	$Vcc = Max., Vo = GND^{(3)}$		-80	-140	-250	mA
VH	Input Hysteresis	_		_	100	-	mV
ICCL	Quiescent Power Supply Current	Vcc = Max		_	5	500	μA
Іссн		VIN = GND or Vcc					
Iccz							

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
lo	Output Drive Current	$Vcc = Max., Vo = 2.5V^{(3)}$		-50	_	-180	mA
Vон	Output HIGH Voltage	Vcc = Min.	IOH = -3mA	2.5	3.5	ı	V
		VIN = VIH or VIL	IOH = -15mA	2.4	3.5	_	V
			$IOH = -32mA^{(4)}$	2	3	_	V
Vol	Output LOW Voltage	Vcc = Min.	IOL = 64mA	_	0.2	0.55	V
		VIN = VIH or VIL					
loff	Input/Output Power Off Leakage ⁽⁵⁾	$VCC = 0V$, $VIN = or Vo \le 4.5V$		_	_	±1	μА

- 1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
- 4. Duration of the condition can not exceed one second.
- 5. This test limit for this parameter is $\pm 5\mu A$ at $T_A = -55^{\circ} C$.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	$VCC = Max.$ $VIN = 3.4V^{(3)}$		_	0.5	1.5	mA
ICCD	Dynamic Power Supply Current ⁽⁴⁾	Vcc = Max., Outputs Open xCEAB and xOEAB = GND xCEBA = Vcc One Input Toggling 50% Duty Cycle	VIN = VCC VIN = GND	_	60	100	μΑ/ MHz
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max., Outputs Open fi = 10MHz 50% Duty Cycle	VIN = VCC VIN = GND	_	0.6	1.5	mA
			VIN = 3.4V VIN = GND	_	0.9	2.3	
		Vcc = Max., Outputs Open fi = 2.5MHz 50% Duty Cycle	VIN = VCC VIN = GND	_	2.4	4.5 ⁽⁵⁾	
		xCEAB, xCEAB and xOEAB = GND xCEBA = Vcc Sixteen Bits Toggling	VIN = 3.4V VIN = GND	_	6.4	16.5 ⁽⁵⁾	

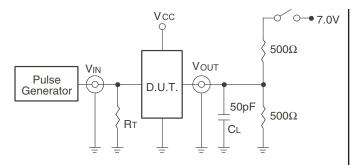
- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. Values for these conditions are examples of the lcc formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
 - $IC = ICC + \Delta ICC DHNT + ICCD (fcpNcp/2 + fiNi)$
 - Icc = Quiescent Current (IccL, IccH and Iccz)
 - ΔIcc = Power Supply Current for a TTL High Input (VIN = 3.4V)
 - DH = Duty Cycle for TTL Inputs High
 - NT = Number of TTL Inputs at DH
 - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 - fcp = Clock Frequency for Register Devices (Zero for Non-Register Devices)
 - NCP = Number of Clock Inputs at fcP
 - fi = Input Frequency
 - Ni = Number of Inputs at fi

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

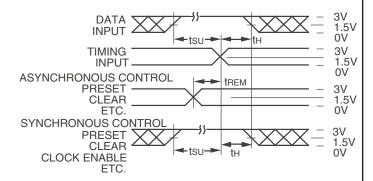
			74FCT16543AT		74FCT1	6543CT	
Symbol	Parameter	Condition ⁽²⁾	Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	Unit
tplh	Propagation Delay	CL = 50pF	1.5	6.5	1.5	5.1	ns
t PHL	Transparent Mode	$RL = 500\Omega$					
	xAx to xBx or xBx to xAx						
tplh	Propagation Delay		1.5	8	1.5	5.6	ns
t PHL	x LEBA to xAx, x LEAB to xBx						
tphz	Output Enable Time		1.5	9	1.5	7.8	ns
tplz	x OEBA or x OEAB to xAx or xBx						
	xCEBA or xCEAB to xAx or xBx						
tpzh	Output Disable Time		1.5	7.5	1.5	6.5	ns
tpzl	x OEBA or x OEAB to xAx or xBx						
	xCEBA or xCEAB to xAx or xBx						
tsu	Set-up Time HIGH or LOW		2	_	2	_	ns
	xAx or xBx to x LEAB or x LEBA						
tΗ	Hold Time HIGH or LOW		2	_	2	_	ns
	xAx or xBx to x LEAB or x LEBA						
tw	xLEAB or xLEBA Pulse Width LOW		4	_	4	_	ns
tsk(o)	Output Skew ⁽³⁾		_	0.5	_	0.5	ns

- 1. See test circuit and waveforms.
- 3. Skew between any two outputs, of the same package, switching in the same direction. This parameter is guaranteed by design.

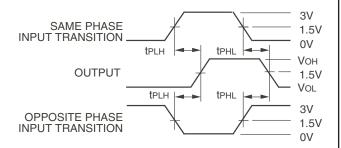
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



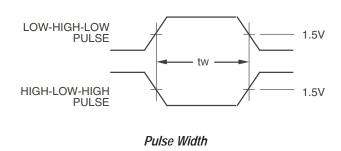
Propagation Delay

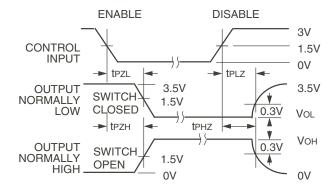
SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

DEFINITIONS:

- CL = Load capacitance: includes jig and probe capacitance.
- RT = Termination resistance: should be equal to ZouT of the Pulse Generator.

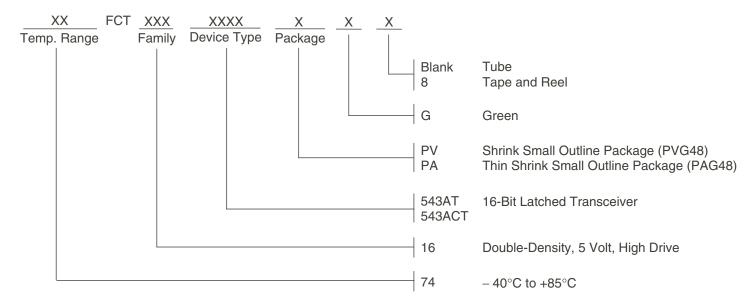




Enable and Disable Times

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; t_F \leq 2.5ns; t_R \leq 2.5ns.

ORDERING INFORMATION



Orderable Part Information

Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
Α	74FCT16543ATPAG	PAG56	TSSOP	I
	74FCT16543ATPAG8	PAG56	TSSOP	I
	74FCT16543ATPVG	PVG56	SSOP	I
	74FCT16543ATPVG8	PVG56	SSOP	I
С	74FCT16543CTPAG	PAG56	TSSOP	I
	74FCT16543CTPAG8	PAG56	TSSOP	I
	74FCT16543CTPVG	PVG56	SSOP	I
	74FCT16543CTPVG8	PVG56	SSOP	I

Datasheet Document History

09/28/2009 Pg. 7 Updated the ordering information by removing the "IDT" notation and non RoHS part.

Added table under pin configuration diagram with detailed package information. Updated the ordering information 07/31/2017 Pg. 1, 2, 5, 7

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